WHAT IS CLAIMED IS:

1. A method of maintaining printed circuit board manufacturing equipment comprising contacting a component of the equipment with a composition including an oxidant.

2. The method of claim 1, wherein the composition is an aqueous solution.

3. The method of claim 1, wherein the oxidant includes a peroxide.

4. The method of claim 1, wherein the composition further comprises a pH modifier.

5. The method of claim 4, wherein the pH modifier includes a carbonate salt.

6. The method of claim 4, wherein the pH modifier is an acid.

7. The method of claim 4, wherein the pH modifier is a base.

8. The method of claim 4, wherein the pH modifier includes sodium carbonate.

9. The method of claim 4, wherein the pH modifier includes acetic acid.

10. The method of claim 1, wherein the component includes a residue.

11. The method of claim 10, wherein the residue includes a resist, a soldermask, an antifoam agent, or a hard water deposit.

12. The method of claim 10, further comprising oxidizing the residue.

13. The method of claim 10, further comprising dispersing the residue.

14. The method of claim 10, further comprising dissolving the residue.

15. The method of claim 1, wherein the component includes a nozzle.

16. The method of claim 15, further comprising passing the composition through the nozzle.

17. The method of claim 15, wherein the component includes a second nozzle.

18. The method of claim 17, further comprising passing the solution through the first nozzle and the second nozzle simultaneously.

19. The method of claim 1, wherein contacting includes maintaining the composition at a temperature greater than 80 °F.

20. The method of claim 1, wherein the oxidant includes hydrogen peroxide.

21. The method of claim 1, wherein the oxidant includes sodium perborate.

22. The method of claim 1, wherein the oxidant includes an organic peroxide, a peracid, or a hydroperoxide.

23. The method of claim 1, wherein the solution includes a surfactant that is not oxidized by the oxidant.

24. The method of claim 1, further comprising removing a waste material from the equipment, the waste material including water, an oxidant, and an oxidized resist.

25. A method of cleaning printed circuit board manufacturing equipment comprising contacting a component of the equipment including a residue with an aqueous composition including an oxidant to oxidize the residue.

26. The method of claim 25, wherein the residue includes a resist, a soldermask, an antifoam agent, or a hard water deposit.

27. The method of claim 25, further comprising dispersing the residue.

28. The method of claim 25, further comprising dissolving the residue.

29. The method of claim 25, wherein the component includes a nozzle.

30. The method of claim 25, wherein the oxidant includes hydrogen peroxide.

31. The method of claim 25, wherein the aqueous composition includes sodium carbonate.

32. The method of claim 25, wherein the aqueous composition includes acetic acid.

33. The method of claim 25, wherein the oxidant includes an organic peroxide, a peracid, or a hydroperoxide.

34. The method of claim 25, further comprising removing a waste material from the equipment, the waste material including water, an oxidant, and an oxidized resist.

35. A method of manufacturing a printed circuit comprising contacting a board including a resist with a composition comprising an oxidant.

36. The method of claim 35, further comprising oxidizing the resist.

37. The method of claim 35, wherein the resist is overplated.

38. The method of claim 35, wherein contacting the board with the composition includes spraying the composition on the board.

39. The method of claim 35, wherein contacting the board with the composition includes immersing the board in the composition.

40. The method of claim 35, wherein the composition includes a pH modifier.

41. The method of claim 40, wherein the pH modifier is an acid.

42. The method of claim 40, wherein the pH modifier is a base.

43. The method of claim 40, wherein the pH modifier includes sodium carbonate.

44. The method of claim 40, wherein the pH modifier includes sodium carbonate and the oxidant include hydrogen peroxide.

45. The method of claim 35, further comprising maintaining the composition at a temperature greater than 80 °F.

46. The method of claim 35, wherein the oxidant includes hydrogen peroxide.

47. The method of claim 35, wherein the oxidant includes sodium perborate.

48. The method of claim 35, wherein the oxidant includes an organic peroxide, a peracid, or a hydroperoxide.

49. The method of claim 35, further comprising removing a waste material from the equipment, the waste material including water, an oxidant, and an oxidized resist.

50. A composition for treating a printed circuit board resist comprising an aqueous solution of an oxidant.

51. The composition of claim 50, further comprising a pH modifier.

52. The composition of claim 51, wherein the pH modifier is a carbonate salt.

53. The composition of claim 52, wherein the concentration of the carbonate salt is between 20 grams per liter and 200 grams per liter.

54. The composition of claim 50, wherein the oxidant includes an organic peroxide, a peracid, or a hydroperoxide.

55. The composition of claim 50, further comprising a surfactant that is not oxidized by the oxidant.

56. The composition of claim 50, wherein the oxidant is hydrogen peroxide.

57. The composition of claim 56, wherein the concentration of hydrogen peroxide is between 2.0% and 10% by volume.

58. The composition of claim 56, further comprising a pH modifier.

59. The composition of claim 58, wherein the pH modifier is a carbonate salt

60. The composition of claim 59, wherein the concentration of hydrogen peroxide is between 2.0% and 10% by volume and the concentration of the carbonate salt is between 20 grams per liter and 200 grams per liter.

61. The composition of claim 59, wherein the concentration of hydrogen peroxide is between 3% and 6% by volume and the concentration of sodium carbonate is between 40 grams per liter and 100 grams per liter.

62. A composition for treating a printed circuit board resist comprising an aqueous solution of hydrogen peroxide and acetic acid.

63. The composition of claim 62, wherein the concentration of hydrogen peroxide is between 2.0% and 10% by volume.

64. The composition of claim 62, wherein the concentration of acetic acid is between 1% and 10% by volume.

65. The composition of claim 62, wherein the concentration of hydrogen peroxide is between 2.0% and 10% by volume and the concentration of acetic acid is between 1% and 10% by volume.

66. The composition of claim 62, wherein the concentration of hydrogen peroxide is between 3% and 6% by volume and the concentration of acetic acid is between 3% and 6% by volume.

67. A composition for treating a printed circuit board resist consisting essentially of an aqueous solution of an oxidant and a pH modifier.

68. A composition for treating a printed circuit board resist consisting essentially of an aqueous solution of hydrogen peroxide and a carbonate salt.